

SILICONE GAP FILLER / PUTTY TGL-X-SI

dispensable

TGL-X-SI is an electrically insulating thermally conductive, highly viscous dispensable form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional crosslinking process. Due to the specific formulation and filling with ceramic particles the material has a extremely high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



Release 09 / 2026

PROPERTIESEN

- ☐ Dispensable
- ☐ Almost zero pressure at assembly due to viscoplasticity
- ☐ Thermal conductivity: 6.5 W/mK
- ☐ Ready-made, no additional crosslinking required

AVAILABILITY

- ☐ Cartridge 50 ml, 300 ml, 5 kg
- ☐ Others on request

APPLICATION EXAMPLES

Thermal link of:

- ☐ SMD packages
 - ☐ Through-hole vias
 - ☐ RDRAMs memory modules
 - ☐ Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs / 5G Telecommunication equipment

Technical Data Sheet

PROPERTY	UNIT	TGL-X-SI
MATERIAL		
Colour		Ceramic filled silicone compound
Density	g/cm ³	Orange
Flow rate	g/s g/min	3.4
Penetration	mm	≥ 30 ¹ 3~4 ²
Shelf Life (from Date of Manufacturing, unopened, dry storage conditions @ < 40°C)	Months	170
Flammability (Equivalent)	UL 94	6
RoHS Conformity	2015 / 863 / EU	V0
		Yes
THERMAL		
Thermal Conductivity ³	W/mK	6.5
Operating Temperature Range	°C	- 40 to + 150
ELECTRICAL		
Dielectric Strength ⁴	kV / mm	≥ 4.5
Volume Resistance	Ohm - cm	1.0 x 10 ¹⁴

Measurement technique according to: ¹ ISO 9048, ² 50 cc / 14# @ 0.42 MPa, ³ ASTM D 5470, ⁴ ASTM D 149. Typical, non-binding values. Not intended for specification purposes. Subject to technical changes. Please contact us for further information.

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